

CORPORATION

承 认 书

SPECIFICATION FOR APPROVAL

客户

CUSTOMER:

存货编码:

品名

DESCRIPTION: SMW7060S701NTT

客户料号:

环保状态:

☐RoHS

☐RoHS+HF

☒RoHS+HF+FP

环保资料:

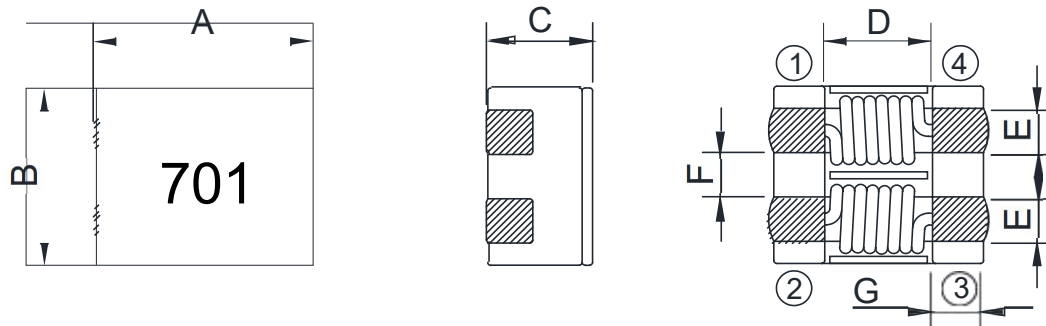
出 图 DRAWING		
发 行 MADE	检 查 CHECKED	承 认 APPROVED
DATE:		

承 认
CUSTOMER APPROVE

Common Mode Choke

1.Appearance and dimensions (mm)

外形尺寸

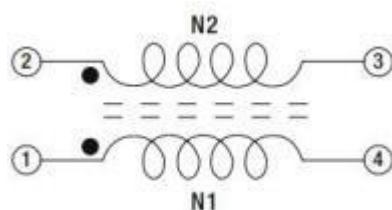


Note: Printing white characters or laser marking
印白字或激光打标

Item	A	B	C	D	E	F	G
Dim	7.0	6.0	3.8	3.5	1.5	1.5	1.7
Tole	±0.5	±0.5	Max	Typ	±0.2	±0.2	±0.2

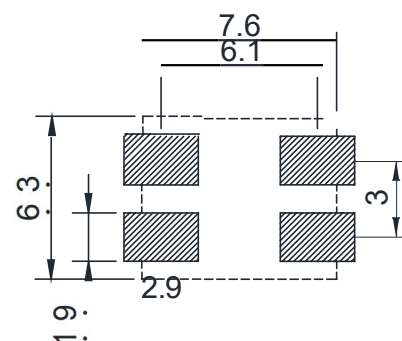
2.Schematic

原理图



3.Reference land pattern (mm)

参考基板尺寸



4.Electrical Properties

电气特性

Part Number 型号	Inductance (uH) Typ. 电感值	Impedance 阻抗值 100MHz/0.1V		D.C.R (mΩ) Max. 直流电阻	Rated Current (A) Max. 额定电流	Rated Voltage (Vdc) Max. 额定电压	Insulation Resistance (MΩ) Min. 绝缘电阻
		Min. Value (Ω)	Typ. Value (Ω)				
SMW7060S400NTT	0.4	40	70	5	15	125	10
SMW7060S101NTT	0.9	100	140	8	9.0	125	10
SMW7060S301NTT	2.4	225	300	10	6.0	125	10
SMW7060S501NTT	3.8	300	500	10	5.0	125	10
SMW7060S701NTT	4.7	500	700	15	4.0	125	10
SMW7060S102NTT	6.0	800	1020	17	3.0	125	10
SMW7060S132NTT	8.0	910	1300	21	2.5	125	10
SMW7060S202NTT	12	1500	2000	50	1.5	125	10
SMW7060S272NTT	14	2000	2700	63	1.0	125	10
SMW7060S302NTT	19	2500	3000	75	0.9	125	10
SMW7060S402NTT	22	3300	4000	100	0.8	125	10

(1). Inductance test condition: 100KHz/0.1V, All data is tested based on 25°C ambient temperature.

电感量测试条件: 100KHz/0.1V, 所有数据都是根据 25°C 环境温度下测试。

(2). Impedance measure condition at 100MHz/0.1V.

共模阻抗测量条件为: 100MHz/0.1V。

(3). Rated current: the value of DC current when the temperature rise is $\Delta T 40^{\circ}\text{C}$ ($T_a = 25^{\circ}\text{C}$).

额定电流: 使产品温度上升到 $\Delta T 40^{\circ}\text{C}$ 时所加载的直流电流值 ($T_a = 25^{\circ}\text{C}$)。

(4). Operating Temperature: -40°C to $+125^{\circ}\text{C}$ (Temperature rise included).

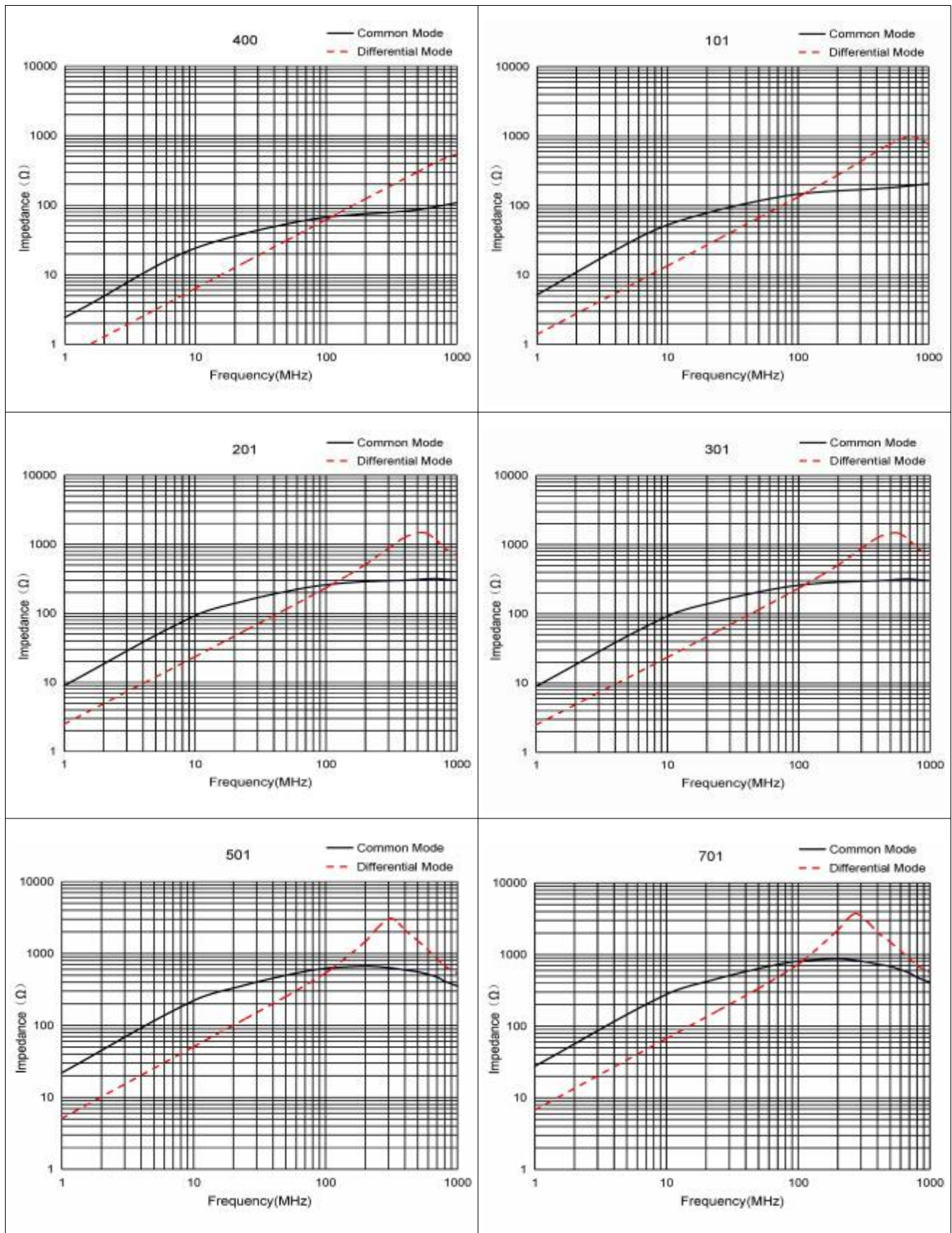
工作温度: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (包括温升)。

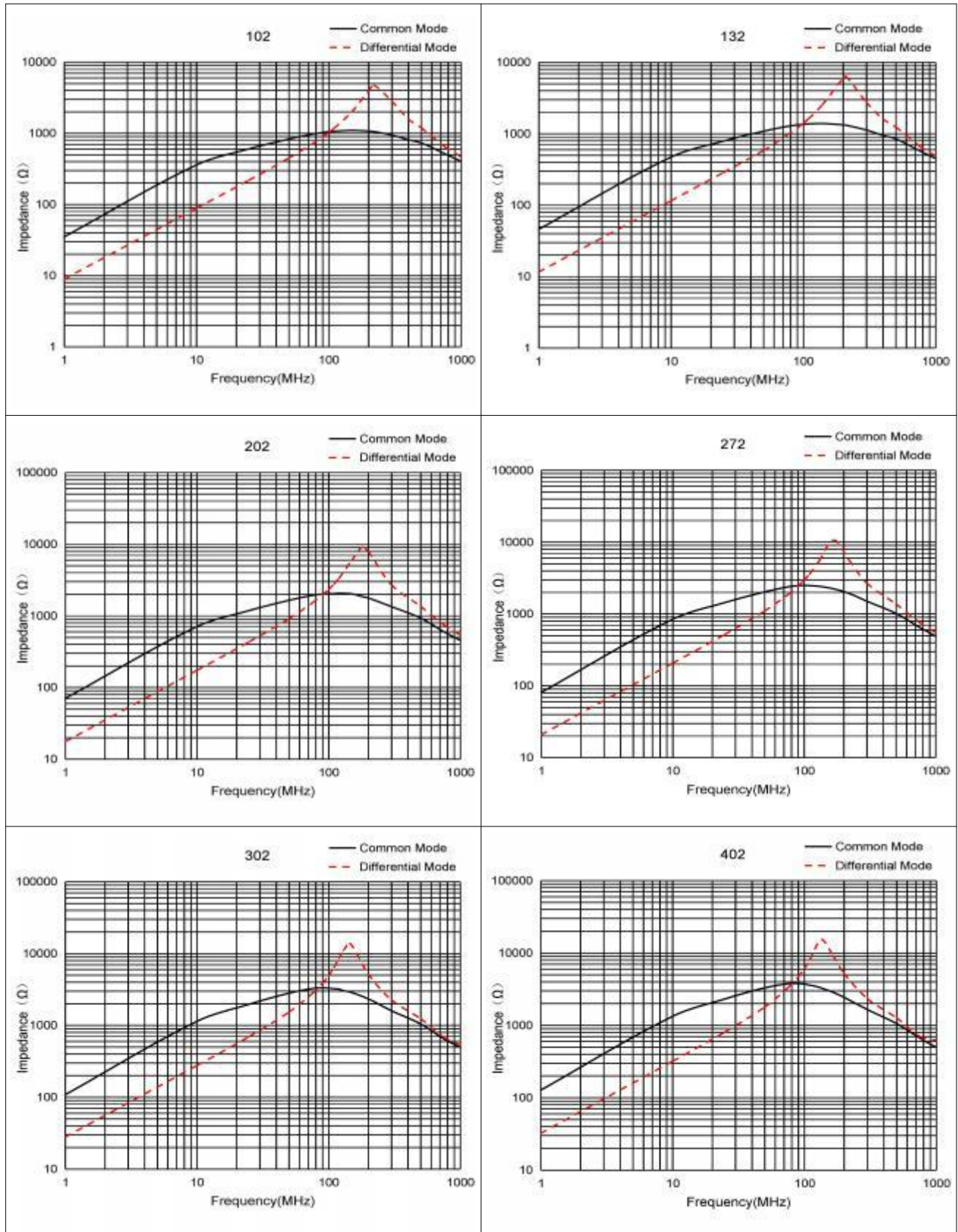
(5). Storage condition: Temperature 5 to 40°C , $\text{RH} \leq 70\%$.

储存条件: 温度 5~ 40°C , 相对湿度小于等于 $\leq 70\%$ 。

5.Impedance vs Frequency Curve

阻抗值 VS 频率曲线





6.Material list

材料清单

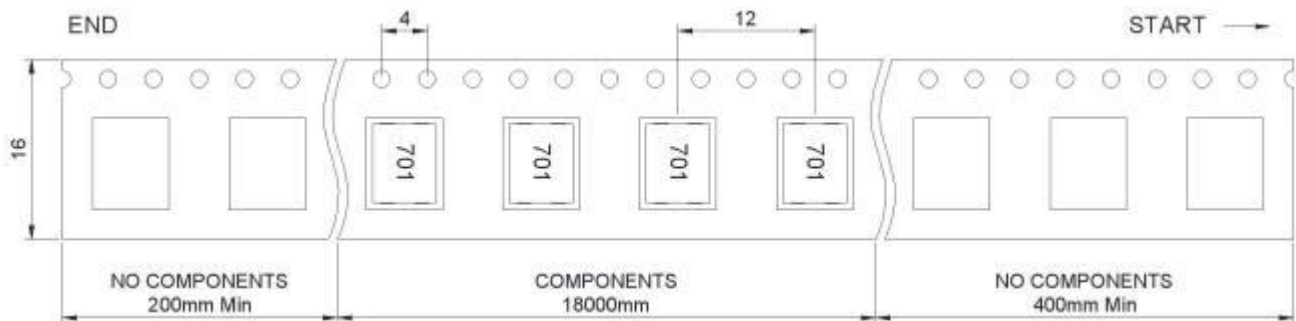
No. 编号	ITEM 项目	DESCRIPTION 描述
1	CORE	FERRITE
2	COVER	LCP E4008
3	WIRE	2UEW-H
4	ADHESIVE	FH-5890
5	TIN	Sn100%
6	INK	WHITE

7.Packing Specification

包装规格

(1).Tape Direction (mm)

编带方向

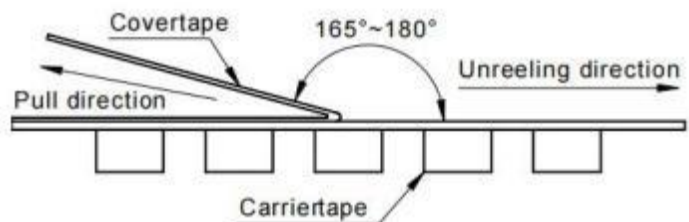


(2).Cover Tape Peel Off Condition

盖带剥离条件

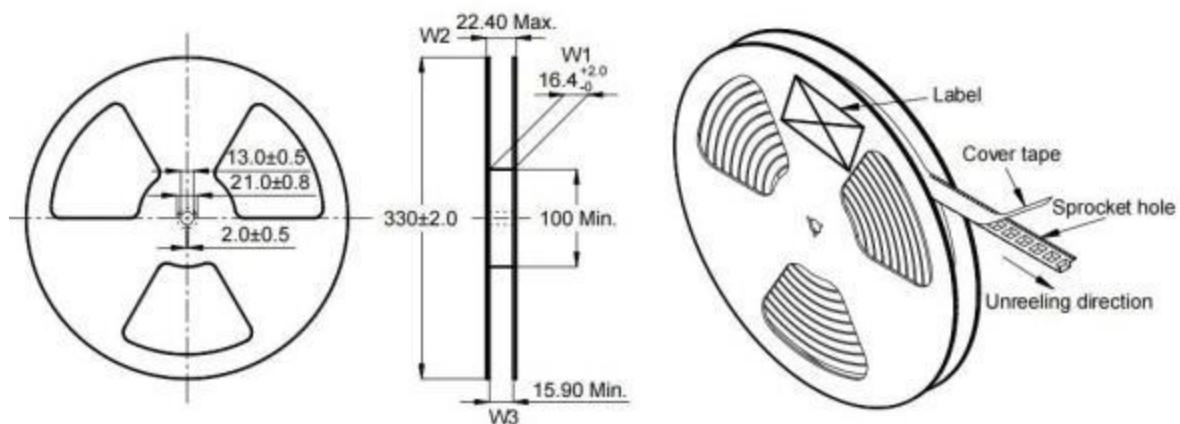
■ Cover tape peel force shall be 10g to 130g.
盖带剥离力度为 10~130 克

■ Reference peel speed 300±10mm/min.
参考剥离速度为 300±10mm/分钟



(3). Reel Dimensions (mm)

卷盘尺寸(mm)



(4). Carton Dimensions and Packing Quantity

包装箱尺寸和包装数量

■ Inner Carton : 340x340x70 mm

内包装盒

■ Out Carton : 360x360x240mm

外包装箱

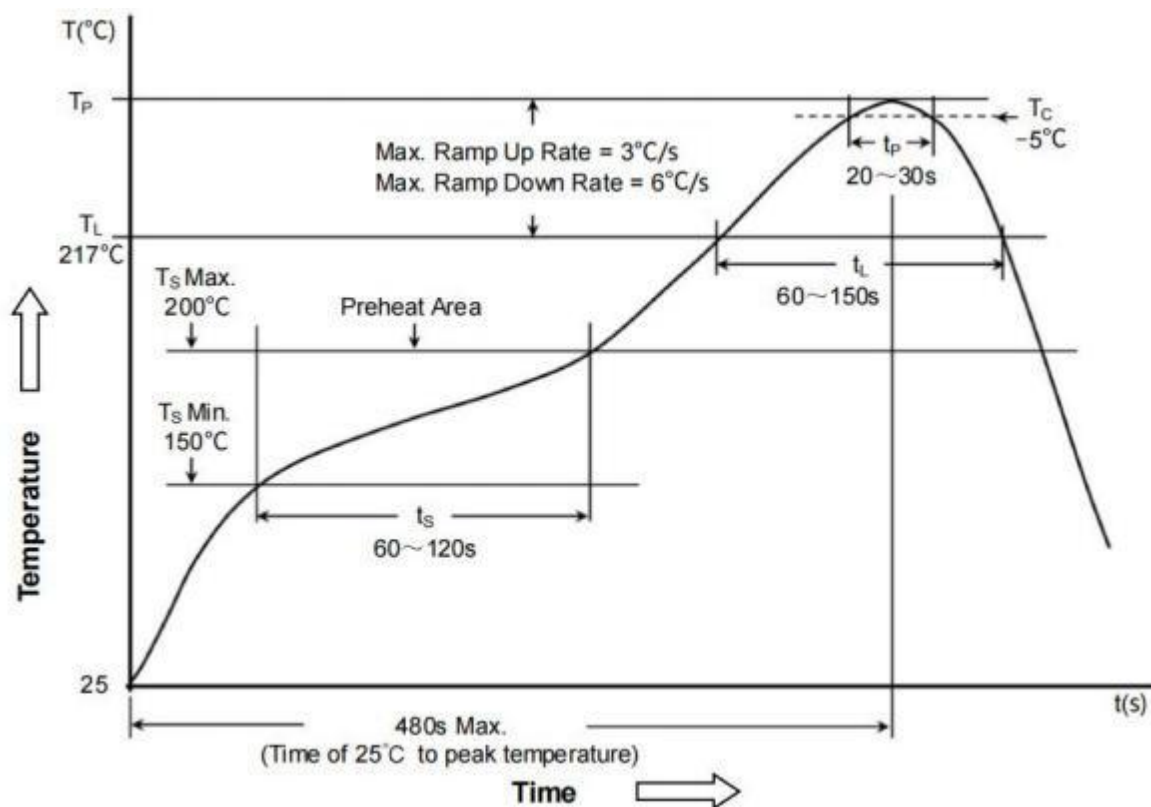
Product Series	Quantity / Reel	Inner Carton Quantity	Out Carton Quantity
SMW7060S701NTT	1500pcs	(1500x3) = 4500pcs	(4500x3) = 13500pcs

8. Soldering Specification

焊接规格

(1). Reflow Profile for SMT Components

SMT 焊锡温度曲线



(2) .Classification of Peak Package Body Temperature (T_P)

封装体峰值温度 (T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		$<350 \text{ mm}^3$	$350 \sim 2000 \text{ mm}^3$	$>2000 \text{ mm}^3$
PB-Free Assembly 无铅装配	$<1.6\text{mm}$	260°C	260°C	260°C
	$1.6 \sim 2.5\text{mm}$	260°C	250°C	245°C
	$\geq 2.5\text{mm}$	250°C	245°C	245°C

■ Reflow is referred to standard IPC/JEDEC J-STD-020D.

回流焊参照标准 IPC/JEDEC J-STD-020D。